

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Kuniaki ONIZAWA</td> <td>04/02/2013</td> </tr> <tr> <td>Hiroshi OHGA</td> <td>04/02/2013</td> </tr> </tbody> </table>		Name	Execution Date	Kuniaki ONIZAWA	04/02/2013	Hiroshi OHGA	04/02/2013				
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<table border="1"> <tr> <td>Name:</td> <td>Hitachi High-Technologies Corporation</td> </tr> <tr> <td>Street Address:</td> <td>24-14, Nishishimbashi 1-chome, Minato-ku</td> </tr> <tr> <td>City:</td> <td>Tokyo</td> </tr> <tr> <td>State/Country:</td> <td>JAPAN</td> </tr> <tr> <td>Postal Code:</td> <td>105-8717</td> </tr> </table>		Name:	Hitachi High-Technologies Corporation	Street Address:	24-14, Nishishimbashi 1-chome, Minato-ku	City:	Tokyo	State/Country:	JAPAN	Postal Code:	105-8717
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CORRESPONDENCE DATA											
Fax Number: 7036108686 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i> Phone: 7036108652 Email: sdavis@milesstockbridge.com Correspondent Name: Mitchell W. Shapiro Address Line 1: 1751 Pinnacle Drive, Suite 500 Address Line 4: McLean, VIRGINIA 22102-3833											
ATTORNEY DOCKET NUMBER:	XA-12329/T6859-19274US01										
NAME OF SUBMITTER:	Sophia L. Davis										
Signature:	/Sophia L. Davis/										
Date:	04/24/2013										
Total Attachments: 1 source=Assignment#page1.tif											

CH \$40.00 13825982

ASSIGNMENT
(譲 渡 証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by HITACHI HIGH-TECHNOLOGIES CORPORATION, a corporation organized under the laws of Japan, located at 24-14, Nishi Shimbashi 1-chome, Minato-ku, Tokyo 105-8717 Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said HITACHI HIGH-TECHNOLOGIES CORPORATION, its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

SAMPLE PROCESSING SYSTEM

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted,

to be held and enjoyed by said HITACHI HIGH-TECHNOLOGIES CORPORATION, its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI HIGH-TECHNOLOGIES CORPORATION.

Signed on the date(s) indicated aside our signatures:

INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1) <u>Kuniaki Onizawa</u> Kuniaki ONIZAWA	<u>4/2/2013</u>
2) <u>Hiroshi Ohga</u> Hiroshi OHGA	<u>4/2/2013</u>
3) <u>Tatsuya Fukugaki</u> Tatsuya FUKUGAKI	<u>4/4/2013</u>
4) _____	_____
5) _____	_____
6) _____	_____
7) _____	_____
8) _____	_____
9) _____	_____
10) _____	_____